

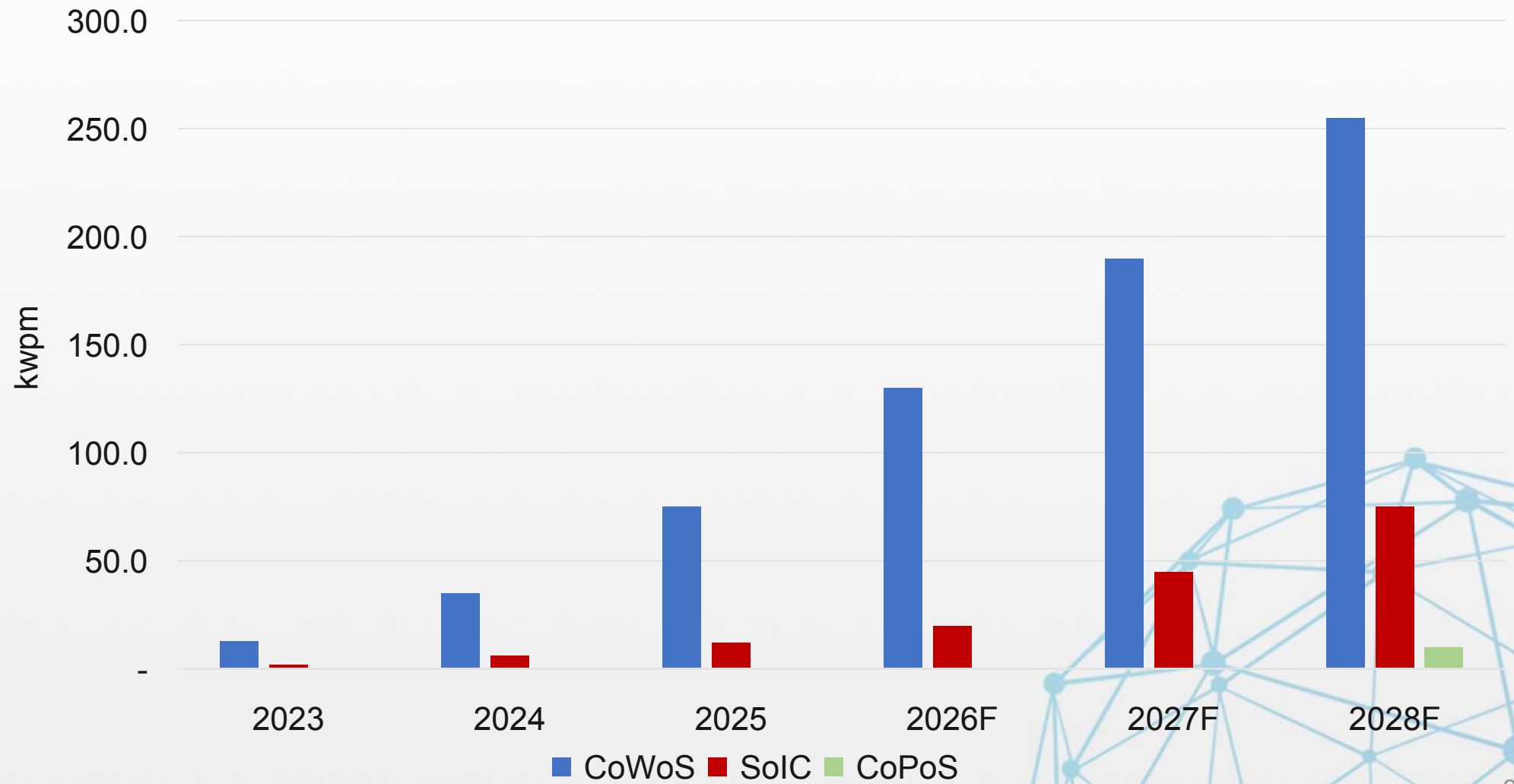


2026年先進封裝產業趨勢



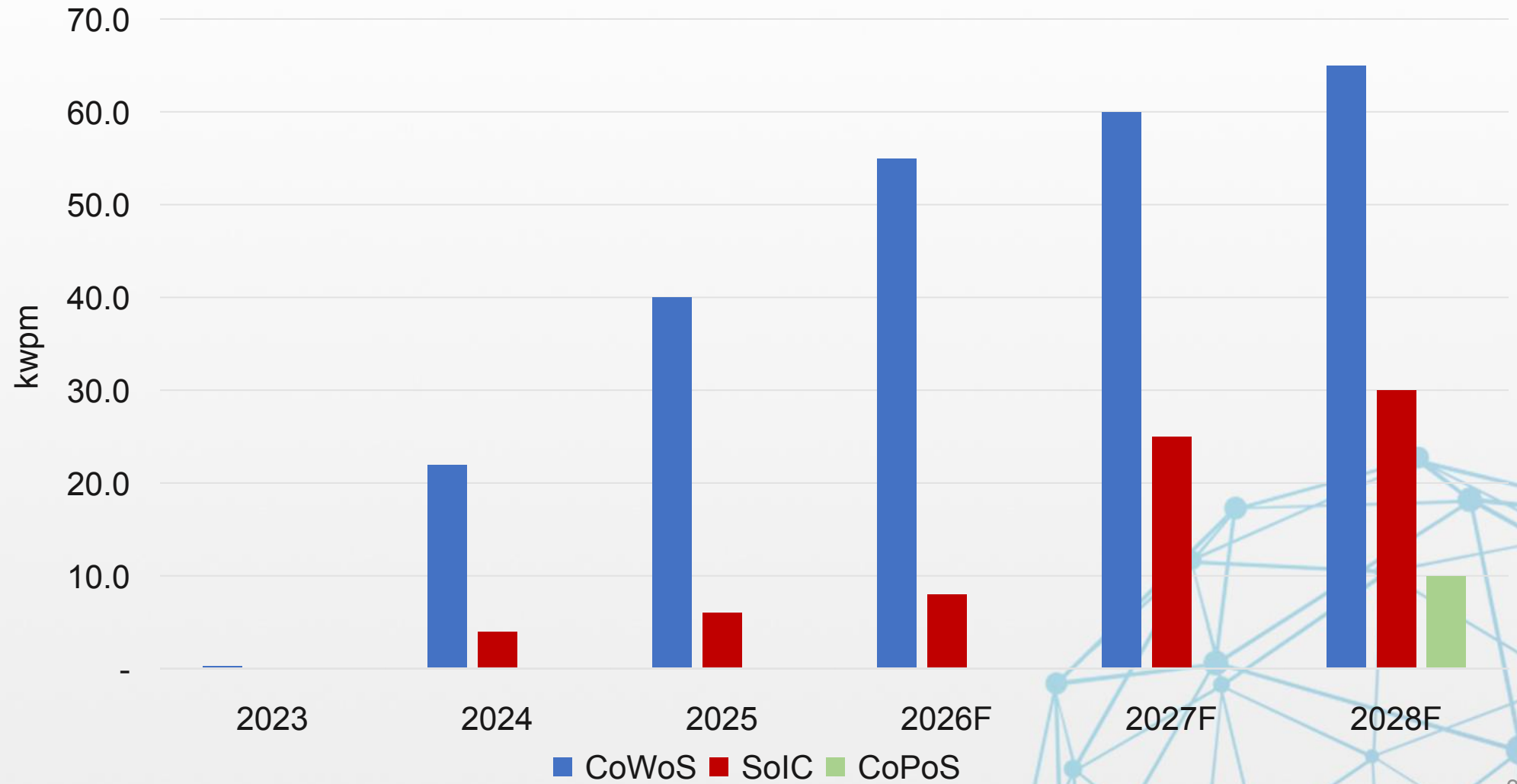


TSMC先進封裝產能預估



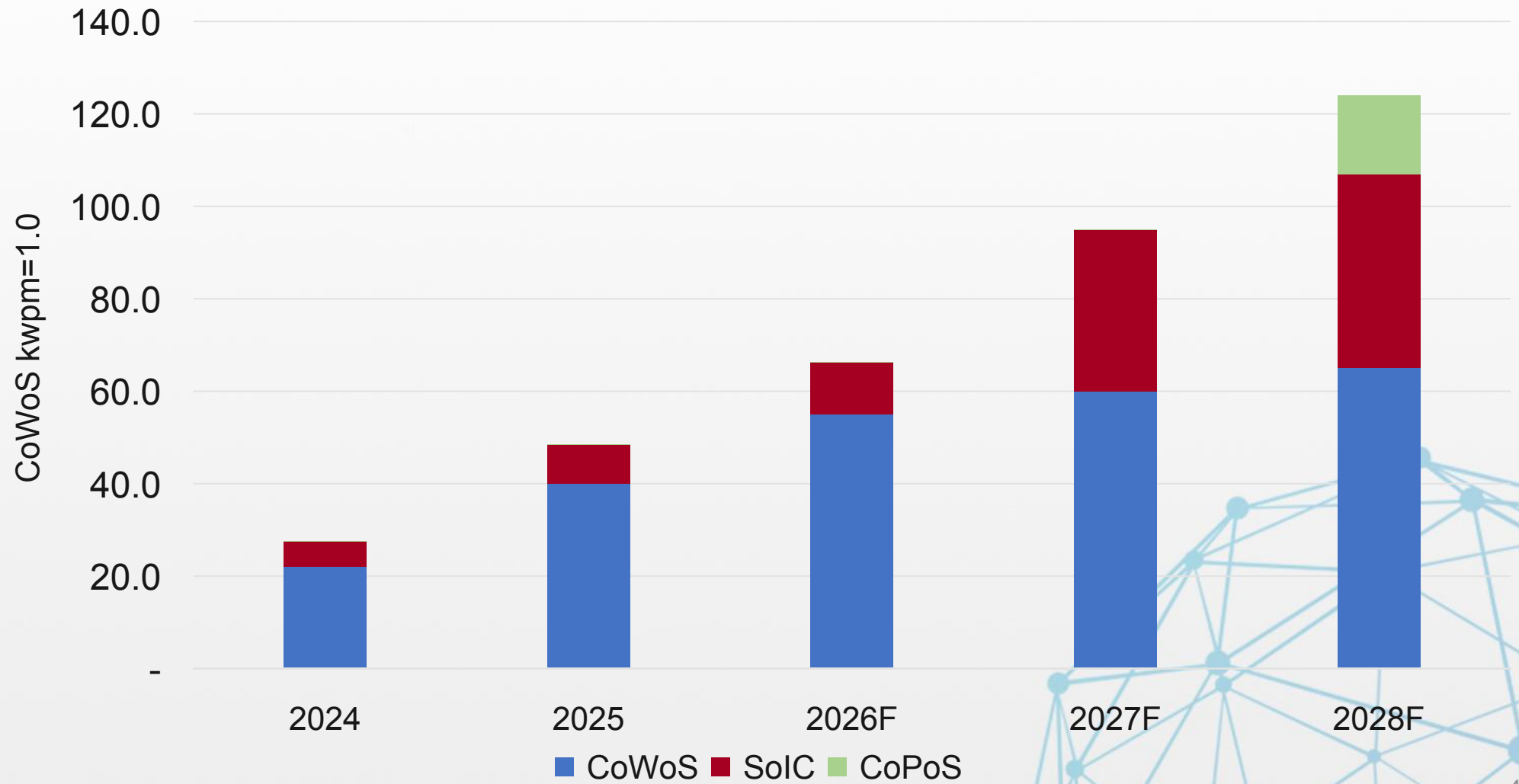


TSMC先進封裝擴產幅度預估



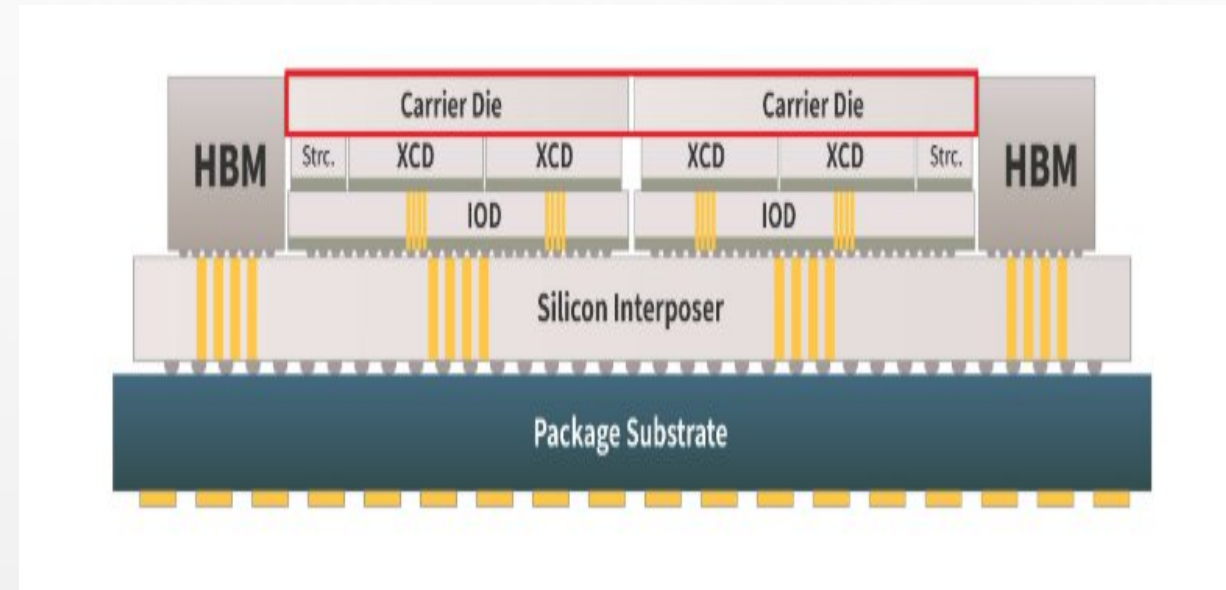
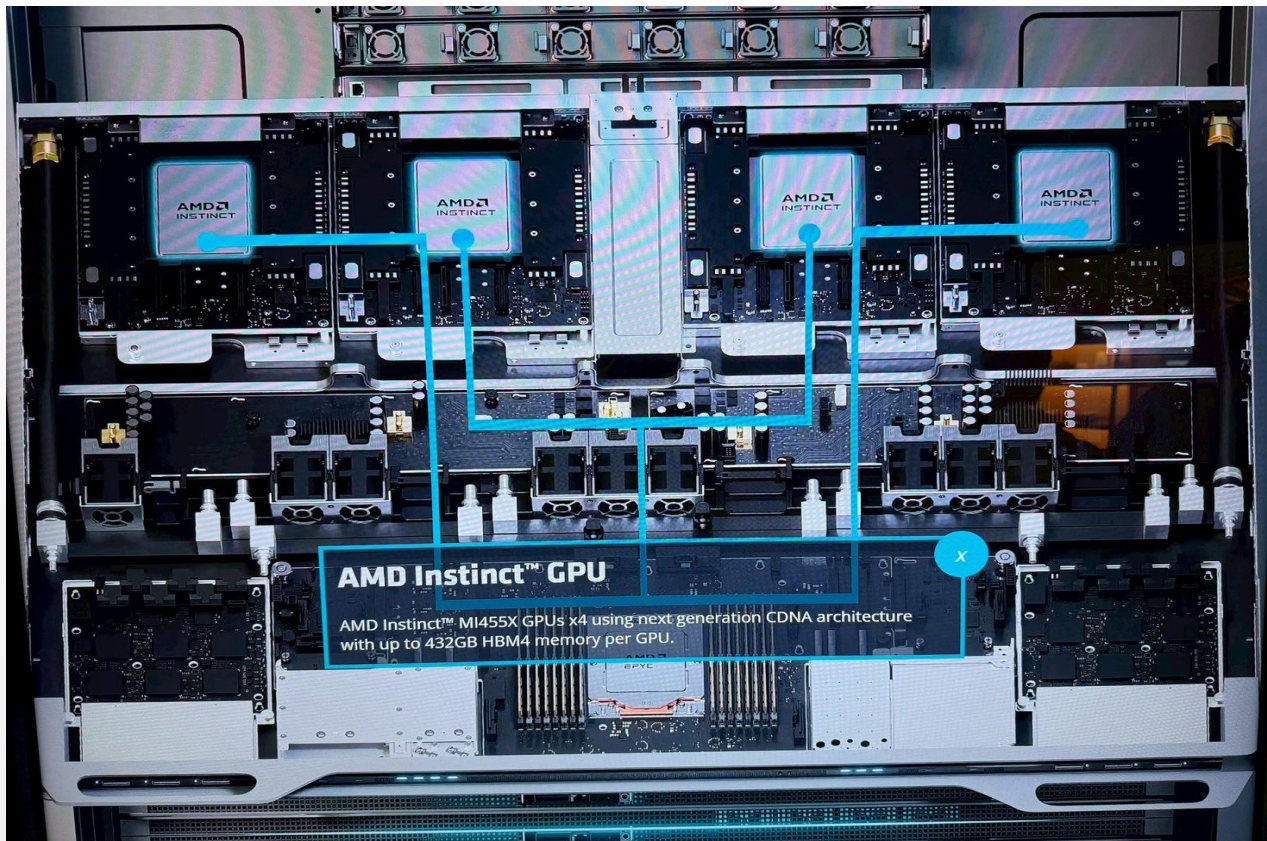


TSMC先進封裝資本投入預估



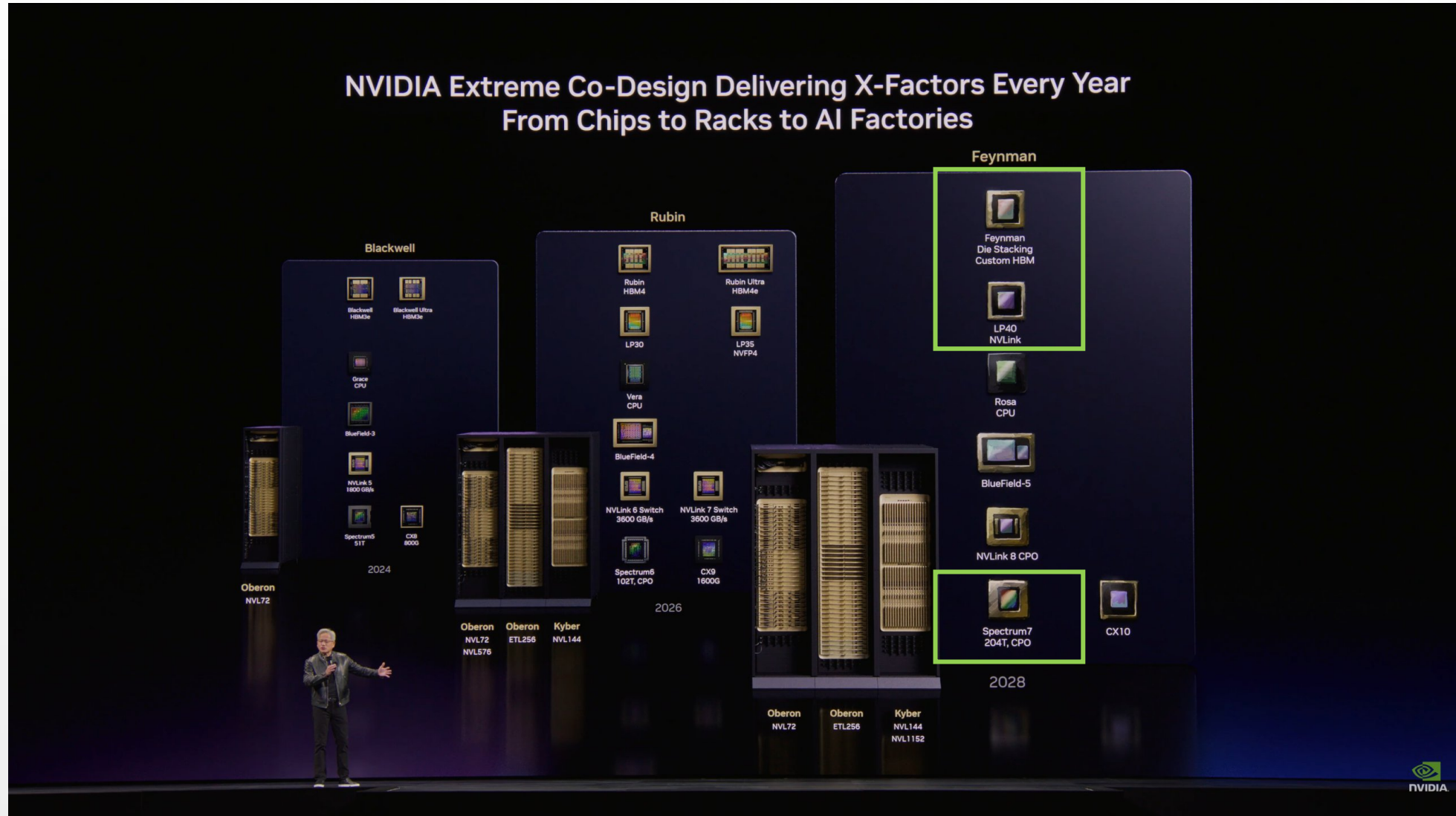


AMD MI450 Helios Compute Tray





NVIDIA AI Roadmap

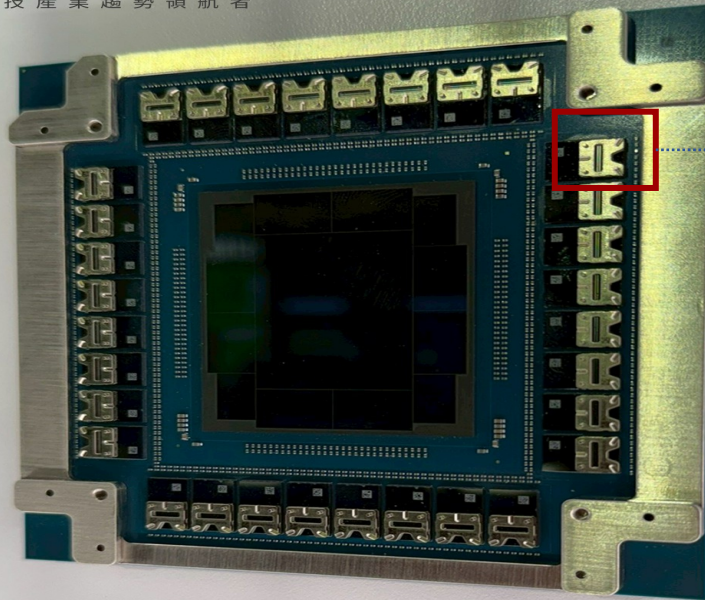




NVIDIA Spectrum-X Switch ASIC



定錨產業筆記
科技產業趨勢領航者

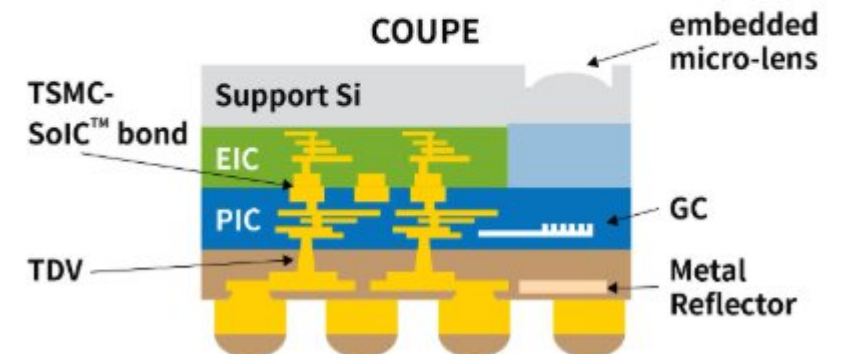


NVIDIA Spectrum-X
Ethernet Photonics

Optical Engine



定錨產業筆記
科技產業趨勢領航者



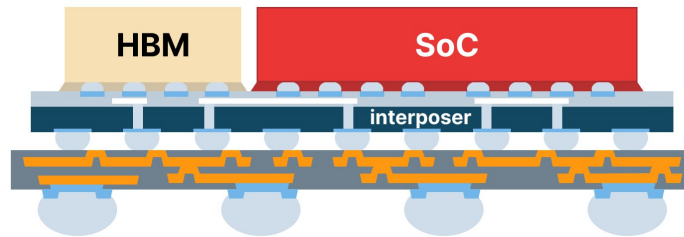


SoIC先進封裝

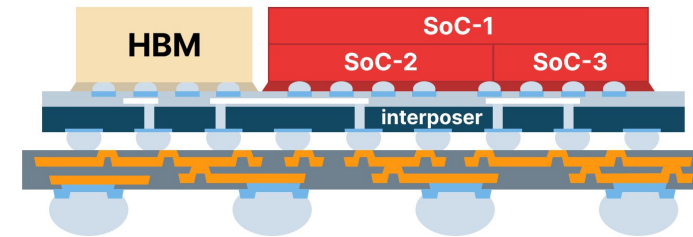


定錨產業筆記
科技產業趨勢領航者

SoC



TSMC-SoIC



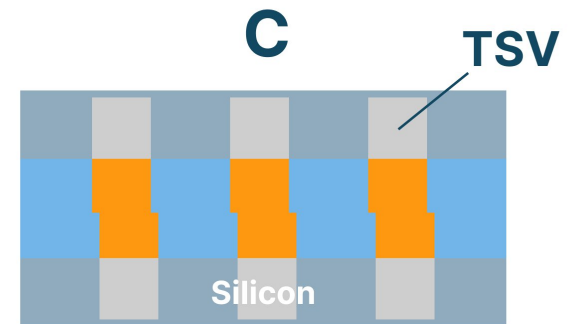
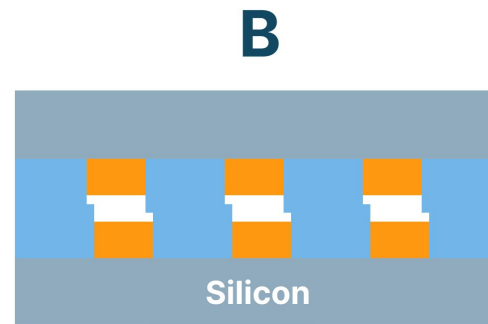
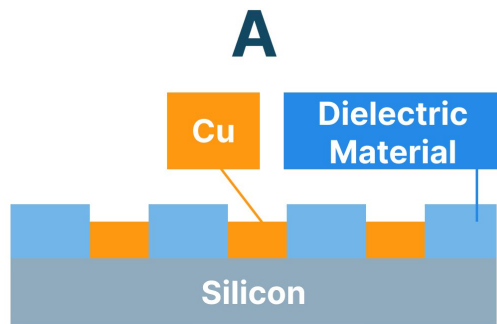


SoIC先進封裝



定錨產業筆記
科技產業趨勢領航者

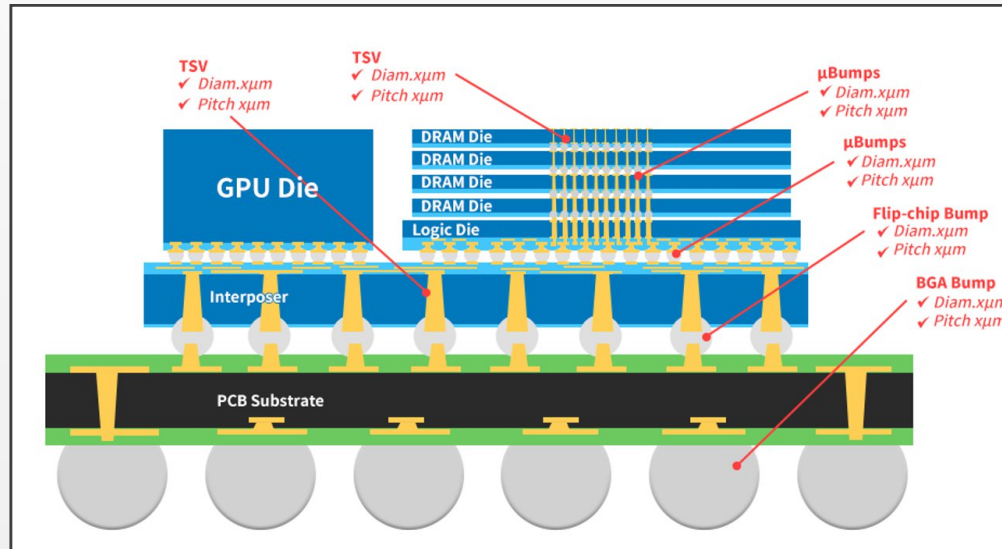
Hybrid bonding



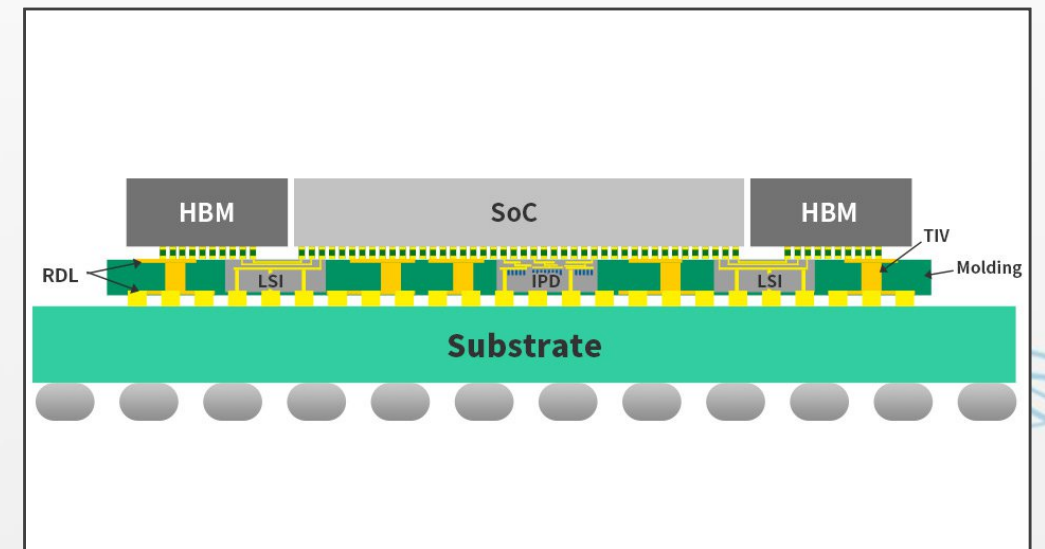


TSMC CoWoS

CoWoS-S

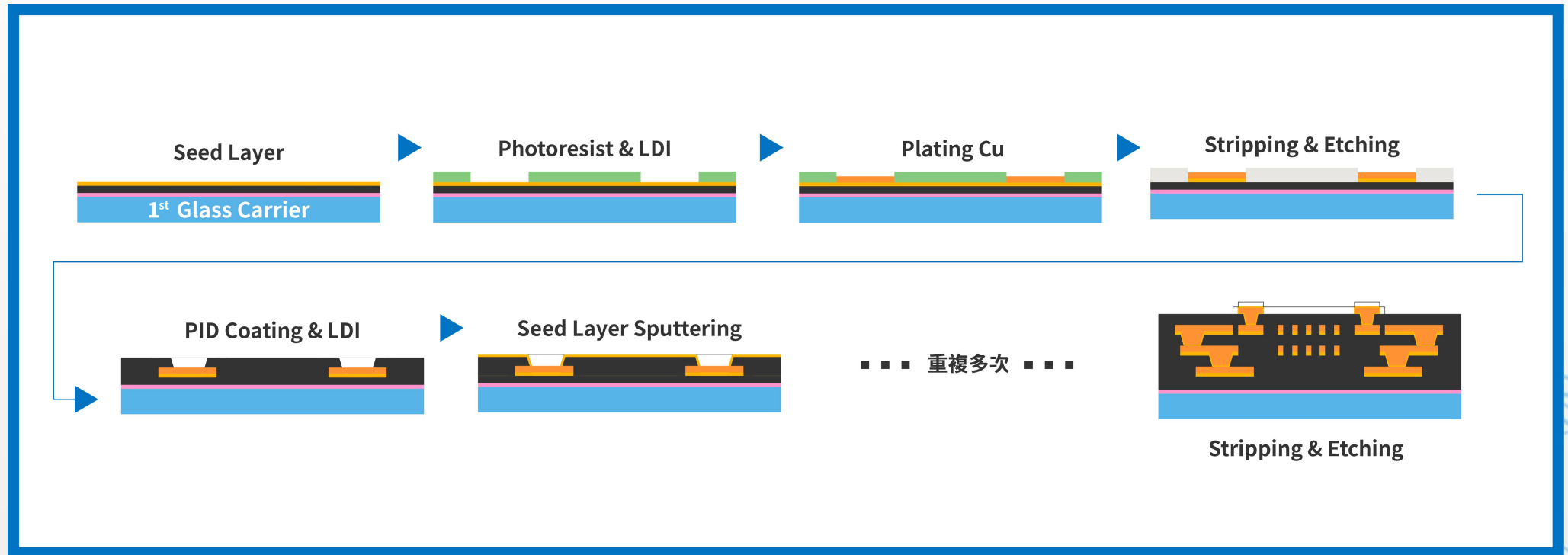


CoWoS-L



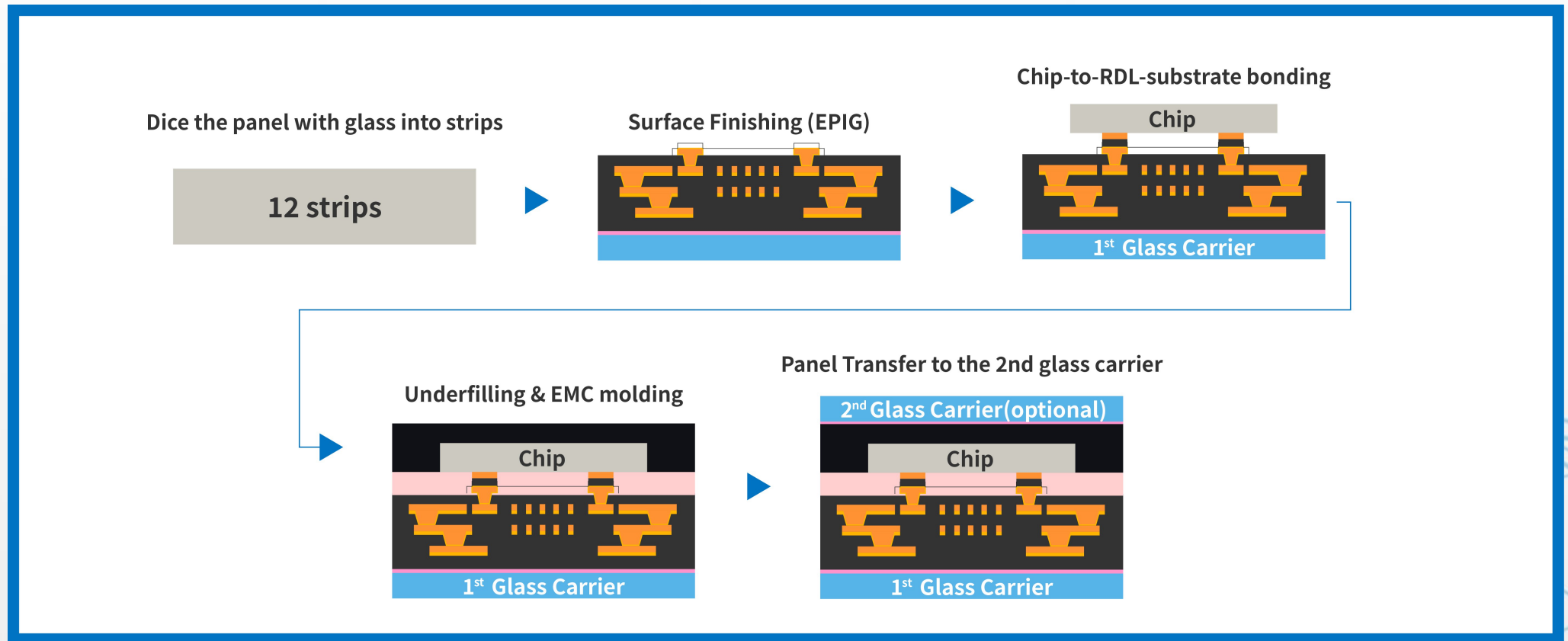


CoWoS-L Process Flow-1





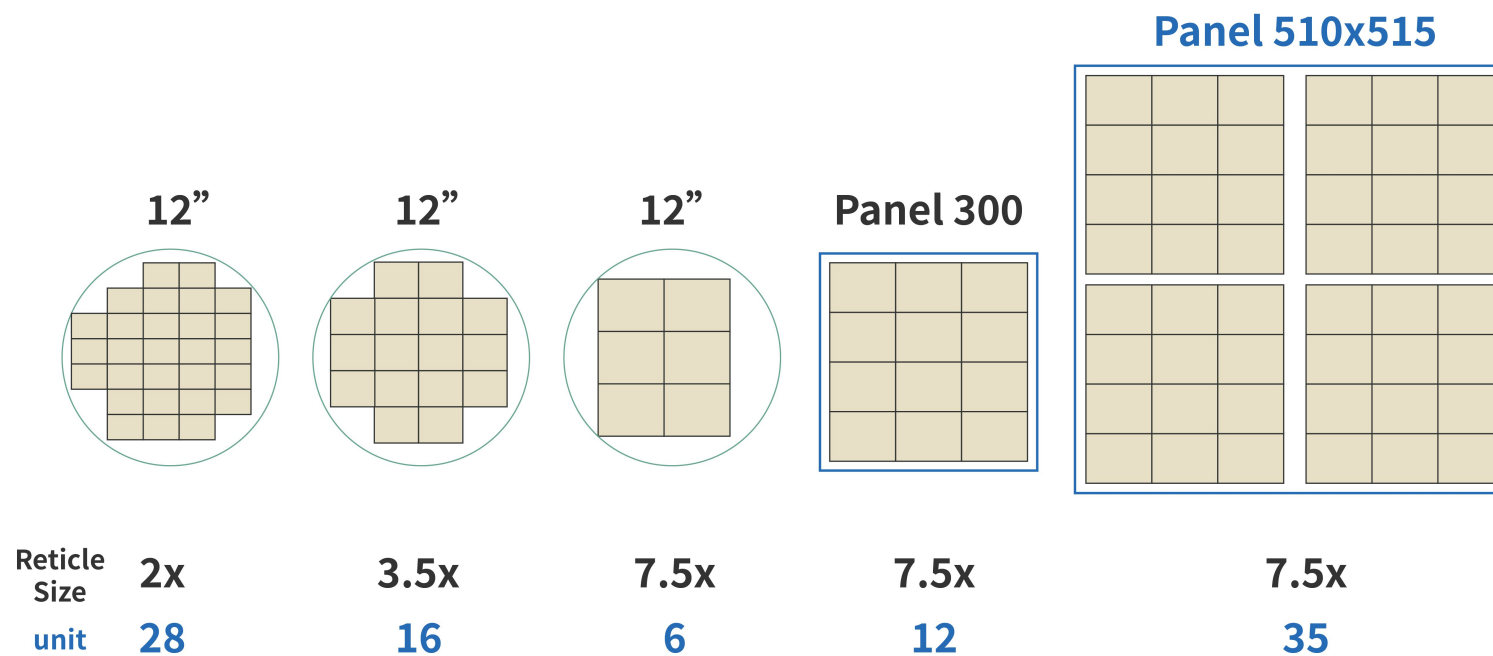
CoWoS-L Process Flow-2





CoPoS

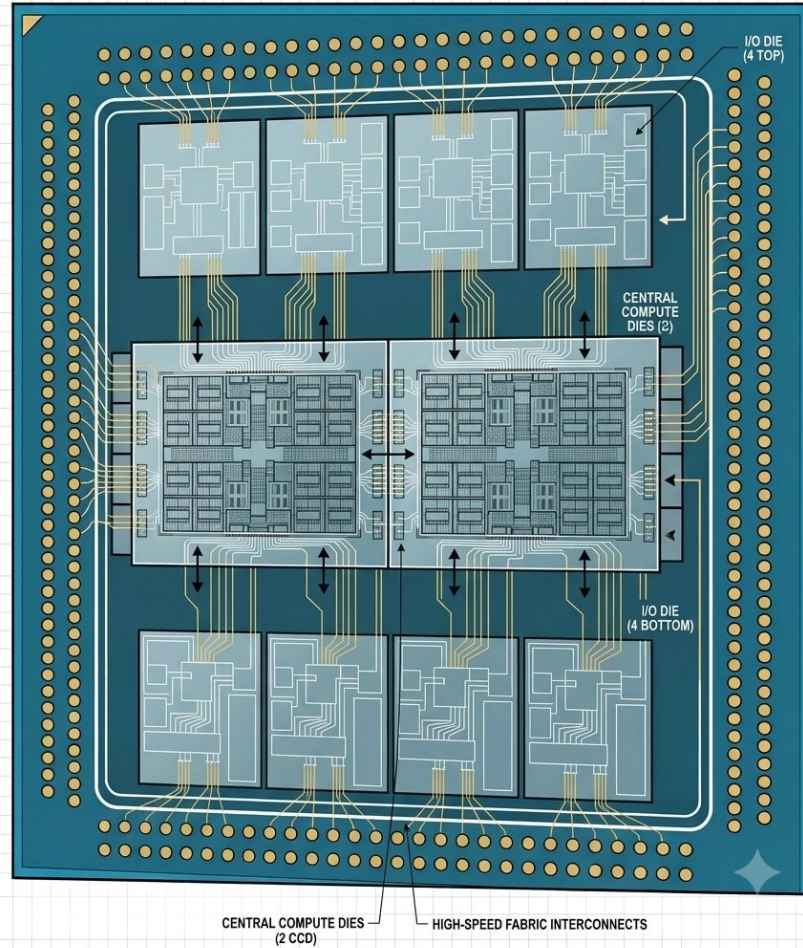
Panel Inevitable as Computility Increases





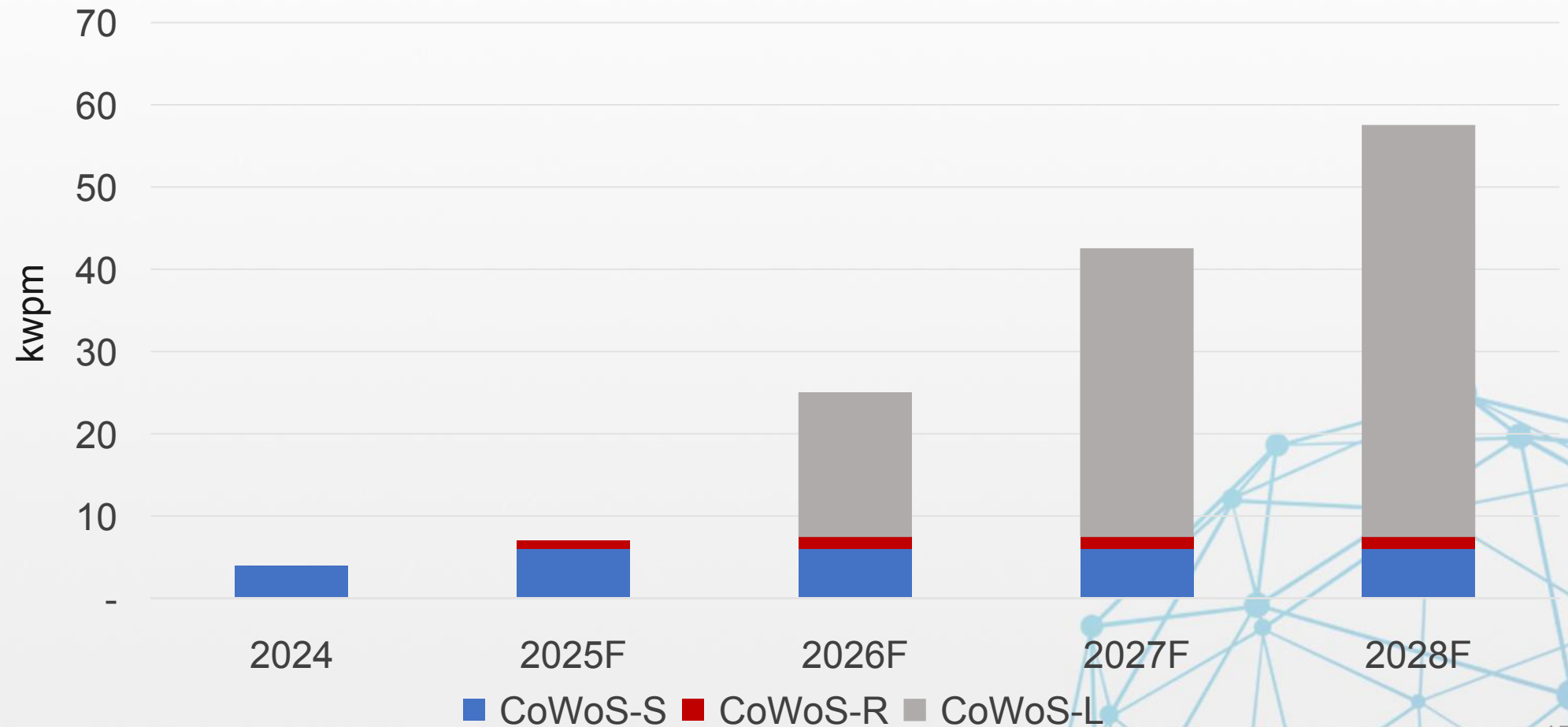
AMD Epyc Venice

REORGANIZED HIGH-PERFORMANCE CPU PACKAGE ARCHITECTURE - SCHEMATIC





ASEH先進封裝產能預估



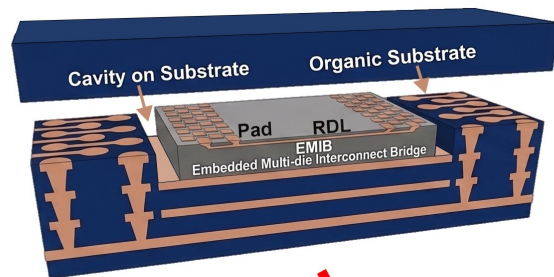


EMIB-T先進封裝

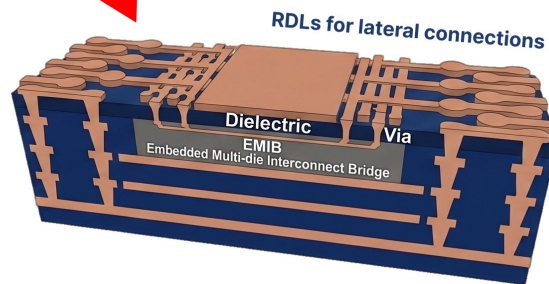


定錨產業筆記
科技產業趨勢領航者

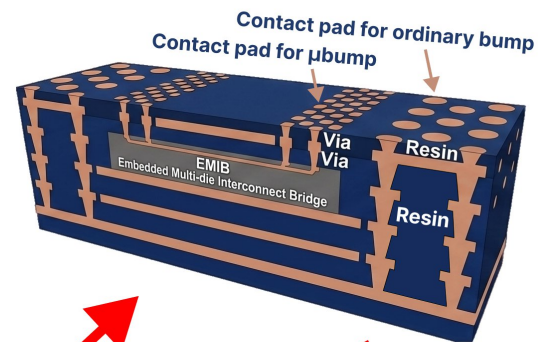
A.



B.



C.



D.

